



General Description

The IPG20N06S4L-26 use advanced SGT MOSFET technology to provide low RDS(ON), low gate charge, fast switching and excellent avalanche characteristics.

This device is specially designed to get better ruggedness and suitable to use in

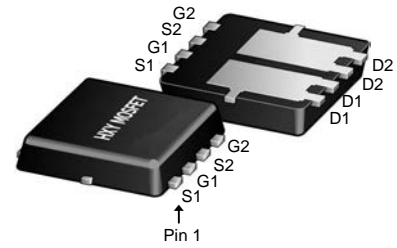
General Features

$V_{DS} = 60V$ $I_D = 50 A$

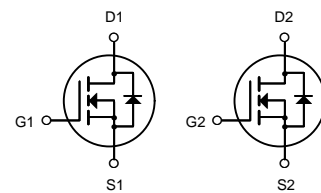
$R_{DS(ON)} < 14m\Omega$ @ $V_{GS} = 10V$

Applications

Consumer electronic power supply Motor control
Synchronous-rectification Isolated DC
Synchronous-rectification applications



DFN5X6-8L



Dual N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
IPG20N06S4L-26	DFN5X6-8L	20N06S4 XXXX	5000

Absolute Maximum Ratings (T_C=25°C unless otherwise specified)

Symbol	Parameter	Max.	Units	
V _{DSS}	Drain-Source Voltage	60	V	
V _{GSS}	Gate-Source Voltage	±20	V	
I _D	Continuous Drain Current	T _C = 25°C	50	A
		T _C = 100°C	29	A
I _{DM}	Pulsed Drain Current ^{note1}	180	A	
E _{AS}	Single Pulsed Avalanche Energy ^{note2}	36	mJ	
P _D	Power Dissipation	T _C = 25°C	60	W
R _{θJC}	Thermal Resistance, Junction to Case	2.5	°C/W	
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +175	°C	



Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =60V, V _{GS} =0V,	-	-	1.0	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±20V	-	-	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.6	2.5	V
R _{DS(on)}	Static Drain-Source on-Resistance <small>note3</small>	V _{GS} =10V, I _D =20A	-	11	14	mΩ
		V _{GS} =4.5V, I _D =10A	-	14	20	
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0V, f=1.0MHz	-	930	-	pF
C _{oss}	Output Capacitance		-	230	-	pF
C _{rss}	Reverse Transfer Capacitance		-	8	-	pF
Q _g	Total Gate Charge	V _{DS} =30V, I _D =20A, V _{GS} =10V	-	22	-	nC
Q _{gs}	Gate-Source Charge		-	4.5	-	nC
Q _{gd}	Gate-Drain("Miller") Charge		-	3.5	-	nC
t _{d(on)}	Turn-on Delay Time	V _{DD} =30V, I _D =20A, R _G =1.6Ω, V _{GS} =10V	-	4.5	-	ns
t _r	Turn-on Rise Time		-	2.7	-	ns
t _{d(off)}	Turn-off Delay Time		-	13.8	-	ns
t _f	Turn-off Fall Time		-	2.7	-	ns
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	45	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	180	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =30A	-	-	1.2	V
t _{rr}	Body Diode Reverse Recovery Time	T _J =25°C, I _F =20A, dI/dt=100A/μs	-	18	-	ns
Q _{rr}	Body Diode Reverse Recovery Charge		-	12	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: T_J=25°C, V_{DD}=30V, V_G=10V, R_G=25Ω, L=0.5mH, I_{AS}=12A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%



Typical Performance Characteristics

Figure 1: Output Characteristics

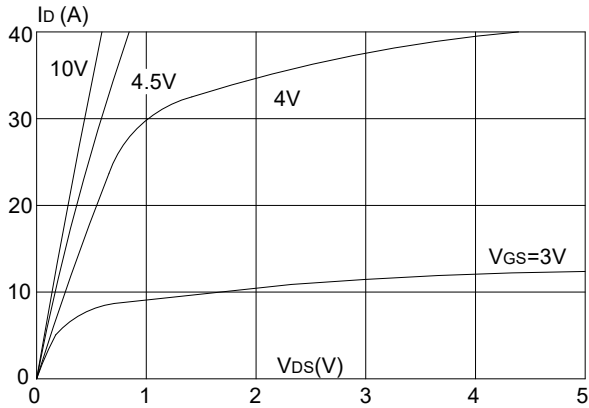


Figure 2: Typical Transfer Characteristics

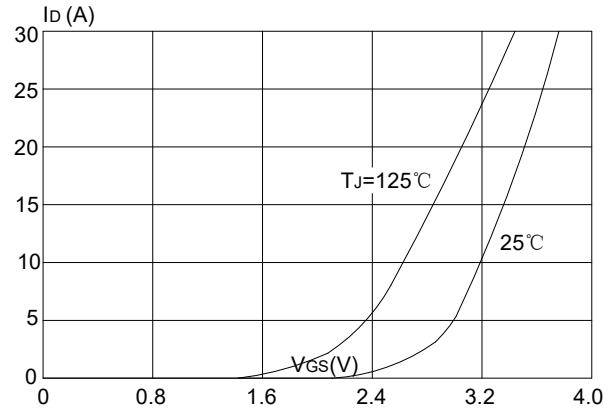


Figure 3: On-resistance vs. Drain Current

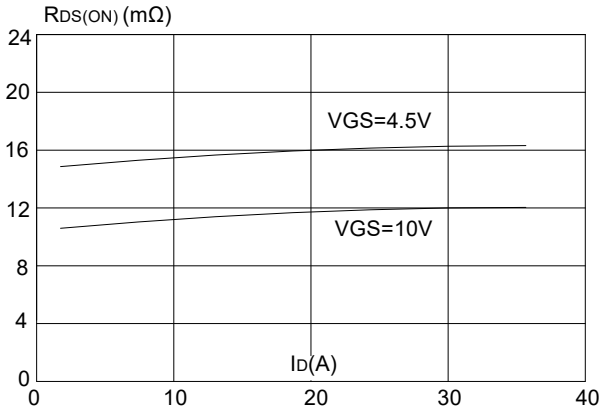


Figure 4: Body Diode Characteristics

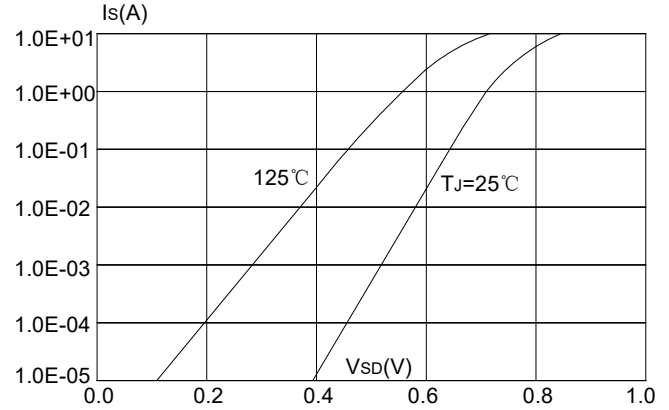


Figure 5: Gate Charge Characteristics

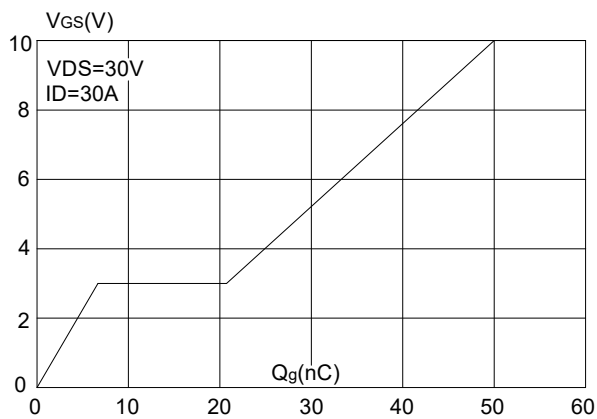


Figure 6: Capacitance Characteristics

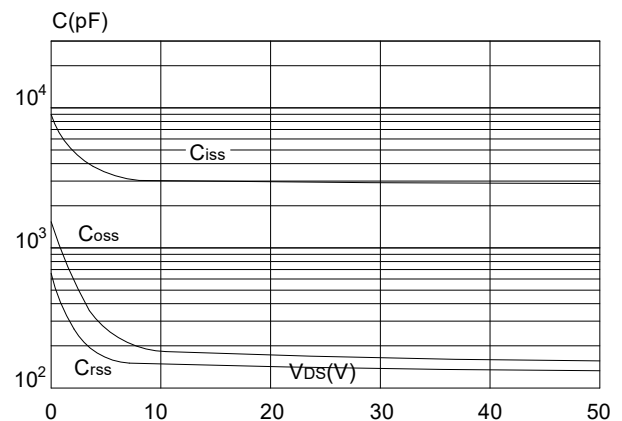




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

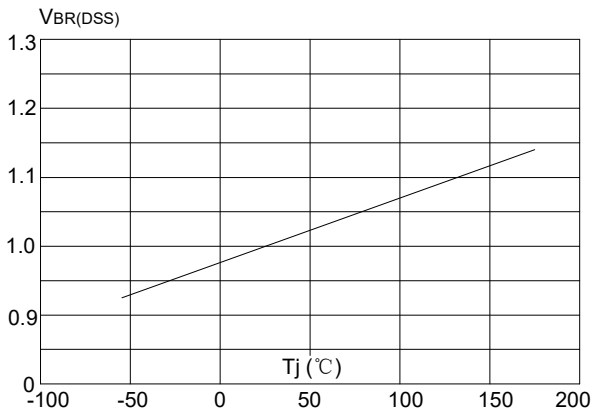


Figure 8: Normalized on Resistance vs. Junction Temperature

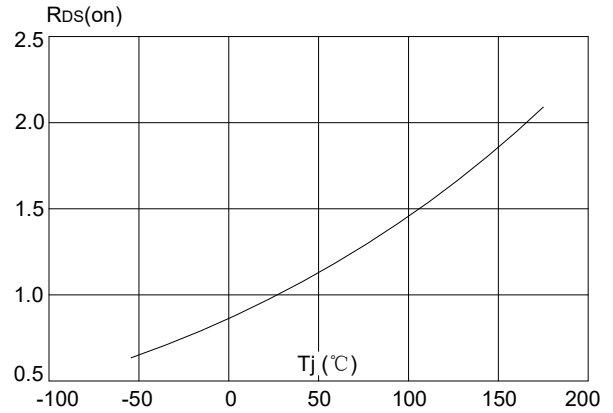


Figure 9: Maximum Safe Operating Area

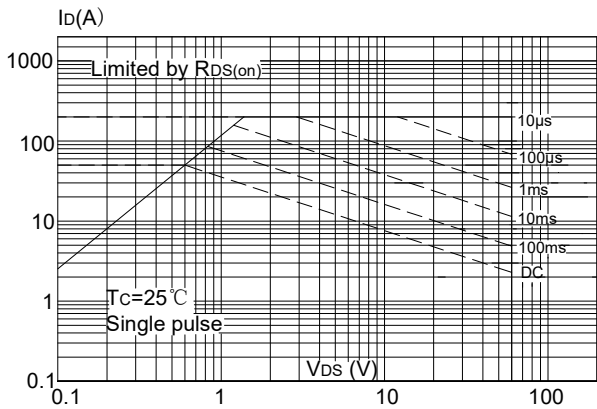


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

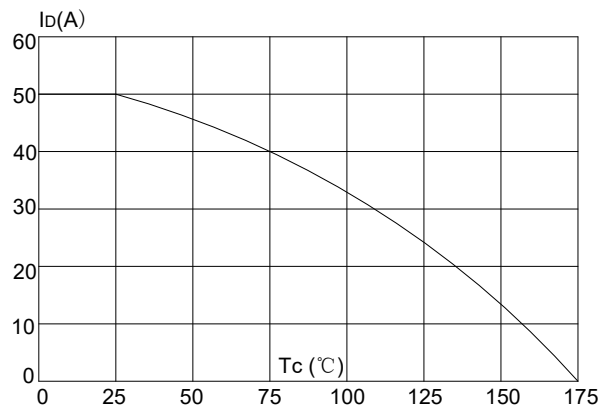
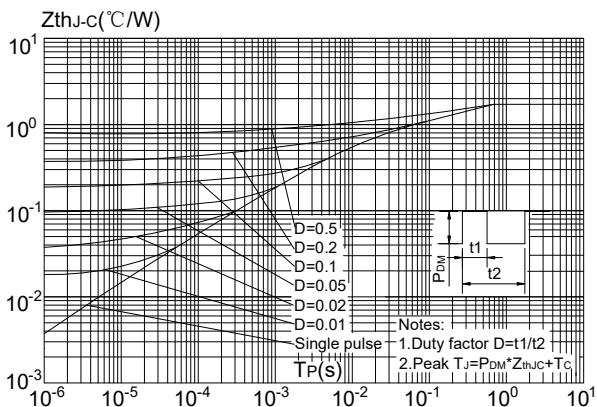
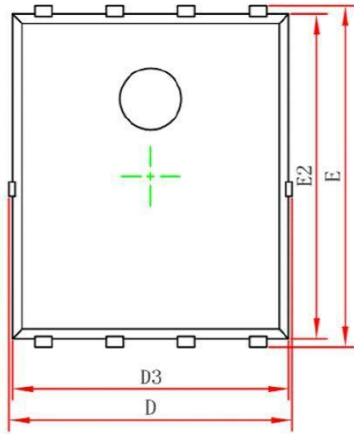


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

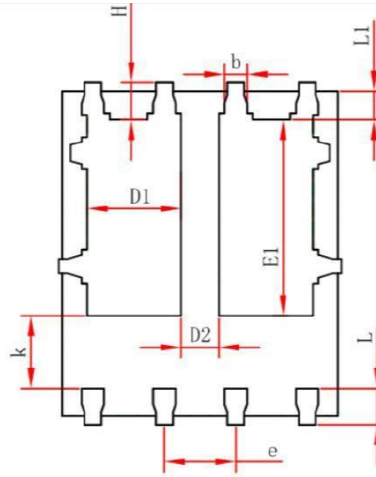




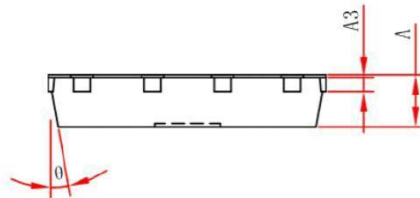
DFN5X6-8L Package Information



Top View



Bottom View



Side View

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.154REF.		0.006REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	1.470	1.870	0.058	0.074
D2	0.470	0.870	0.019	0.034
E1	3.375	3.575	0.133	0.141
D3	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°



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